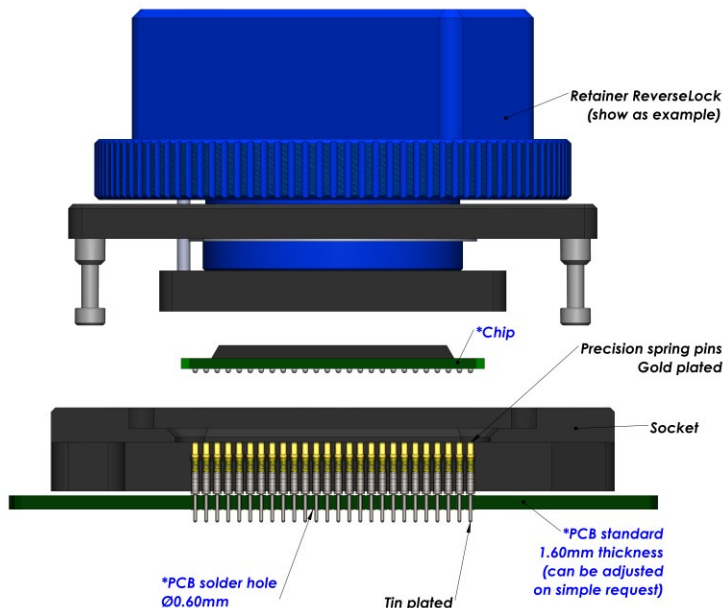
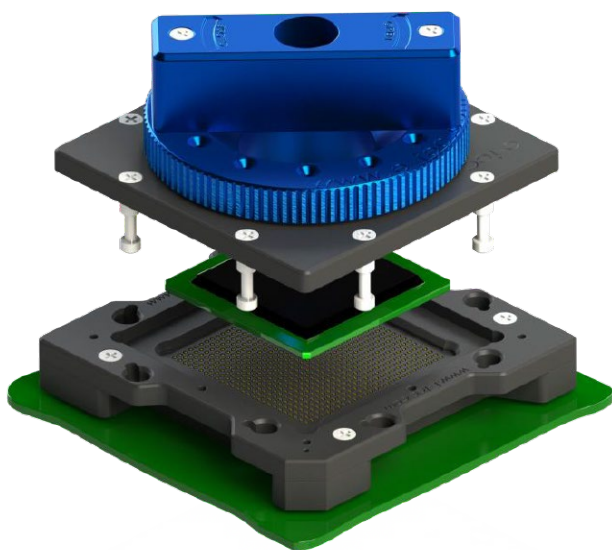


Through-hole (THT) soldering Test Socket

For BGA / Bumped chip / WLCSP / eMMC Package

1.27 mm pitch (from 1.27 mm upwards)



E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 1270			
Application	Through-hole technology	Force	25 gr
Mounting	THT	Current rating	2.2 A
Bandwidth (GHz@-1dB)	3 GHz	Capacitance pF	< 1 pF
Contact resistance	<100mOhm	Inductance nH	< 2 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

How to order

BU # #### -127# - ##### #5 #

Shape of tip

U : Concave

Options:

P : Pointed

S : Spring

C : Crown

Nbr of contacts

Depends on ballcount of chip

Contact type

70 : Standard THT

72 : Special THT to plug into MGS adapters

Plating

95: Tin / Gold

55: Gold / Gold

Other on request

Option code (see page 16-19)

D : Dead bug

M : Multi frames

U : Multi packages

S : Custom opening slot

L : Locating pegs

A : Alignment plate

H : Heatsink

F : Fan + Heatsink

P : Thermal drain pad

W : Transparent lid

I : Steel retention lid

B : Aluminium retention lid

T : Torque tool fixture

G : Handling button

Retention frame type (Lid) (see page 12-15)

W: TwistLock

F : FastLock

B : SpringLock

H : Open Clamshell Alu (<200 contacts)

J : Clamshell Alu (>200 contacts)

L : Open Lever Clamshell Alu (>200 contacts)

S : ScrewLock

Q : Open QuickLock (<200 contacts)

D : QuickLock (>200 contacts)

M : Injection Molded ClamShell

R : ReverseLock

T : SlimLock

Grid code / Config. code

Will be given by the factory after receipt of the chip datasheet